Lattice Semiconductor Corporation - LFSC3GA80E-7FC1704C Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	20000
Number of Logic Elements/Cells	80000
Total RAM Bits	5816320
Number of I/O	904
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1704-BCBGA, FCBGA
Supplier Device Package	1704-CFCBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfsc3ga80e-7fc1704c

DLLs and dynamic glitch free clock MUXs which are required in today's high end system designs. High-speed, high-bandwidth I/O make this family ideal for high-throughput systems.

The ispLEVER® design tool from Lattice allows large complex designs to be efficiently implemented using the LatticeSC family of FPGA devices. Synthesis library support for LatticeSC is available for popular logic synthesis tools. The ispLEVER tool uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeSC device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-designed IP (Intellectual Property) ispLeverCORE™ modules for the LatticeSC family. By using these IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

Innovative high-performance FPGA architecture, high-speed SERDES with PCS support, sysMEM embedded memory and high performance I/O are combined in the LatticeSC to provide excellent performance for today's leading edge systems designs. Table 1-3 details the performance of several common functions implemented within the LatticeSC.

Table1-3. Speed Performance for Typical Functions[1]

Functions	Performance (MHz)[2]
32-bit Address Decoder	539
64-bit Address Decoder	517
32:1 Multiplexer	779
64-bit Adder (ripple)	353
32x8 Distributed Single Port (SP) RAM	768
64-bit Counter (up or down counter, non-loadable)	369
True Dual-Port 1024x18 bits	372
FIFO Port A: x36 bits, B: x9 bits	375

1. For additional information, see Typical Building BLock Function Performance table in this data sheet.
2. Advance information (-7 speed grade).

Figure 2-3. Slice Diagram

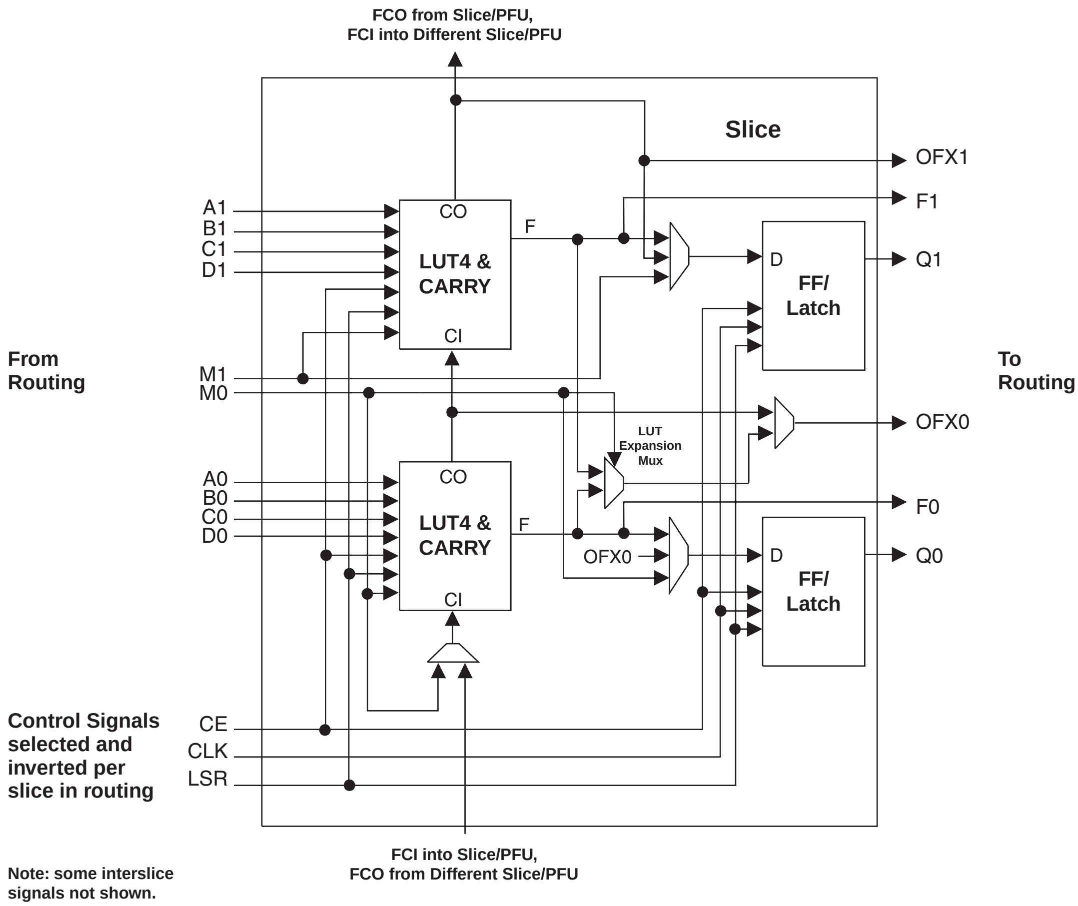


Table 2-1. Slice Signal Descriptions

Function	Type	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0	Multipurpose Input
Input	Multi-purpose	M1	Multipurpose Input
Input	Control signal	CE	Clock Enable
Input	Control signal	LSR	Local Set/Reset
Input	Control signal	CLK	System Clock
Input	Inter-PFU signal	FCI	Fast Carry In[1]
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register Outputs
Output	Data signals	OFX0	Output of a LUT5 MUX
Output	Data signals	OFX1	Output of a LUT6, LUT7, LUT8[2] MUX depending on the slice
Output	Inter-PFU signal	FCO	For the right most PFU the fast carry chain output[2]

1. See Figure 2-2 for connection details.
2. Requires two PFUs.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR 16x2 x 4 DPR 16x2 x 2	ROM 16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR 16x4 x 2 DPR 16x4 x 1	ROM 16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR 16x8 x 1	ROM 16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM 16x8 x1

Routing

There are many resources provided in the LatticeSC devices to route signals individually or as busses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

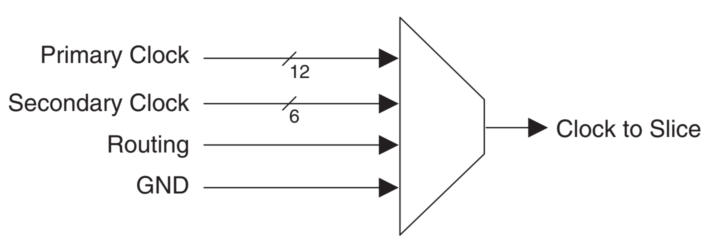
The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU) resources. The x1 and x2 connections provide fast and efficient connections in horizontal, vertical and diagonal directions. All connections are buffered to ensure high-speed operation even with long high-fanout connections.

The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

sysCLOCK Network

The LatticeSC devices have three distinct clock networks for use in distributing high-performance clocks within the device: primary clocks, secondary clocks and edge clocks. In addition to these dedicated clock networks, users are free to route clocks within the device using the general purpose routing. Figure 2-4 shows the clock resources available to each slice.

Figure 2-4. Slice Clock Selection



Note: GND is available to switch off the network.

Primary Clock Sources

LatticeSC devices have a wide variety of primary clock sources available. Primary clocks sources consists of the following:

- Primary clock input pins
- Edge clock input pins
- Two outputs per DLL

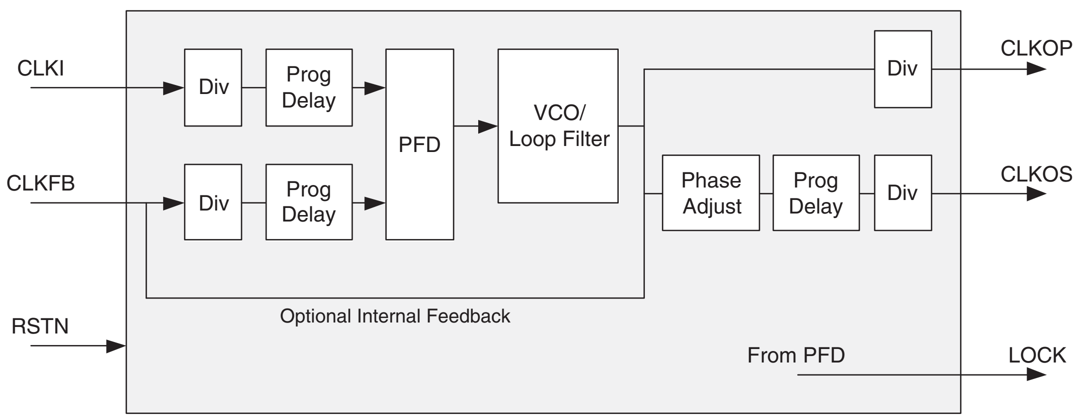
The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically.

The Phase Select block can modify the phase of the clock signal if desired. The Spread Spectrum block supports the modulation of the PLL output frequency. This reduces the peak energy in the fundamental and its harmonics providing for lower EMI (Electro Magnetic Interference).

The sysCLOCK PLL can be configured at power-up and then, if desired, reconfigured dynamically through the serial memory interface bus which connects with the on-chip system bus. For example, the user can select inputs, loop filters, divider setting, delay settings and phase shift settings. The user can also directly access the SMI bus through the routing.

The PLL clock input, from pin or routing, feeds into an input divider. There are four sources of feedback signal to the feedback divider: from the clock net, directly from the voltage controlled oscillator (VCO) output, from the routing or from an external pin. The signal from the input clock divider and the feedback divider are passed through the programmable delay before entering the phase frequency detector (PFD) unit. The output of this PFD is used to control the voltage controlled oscillator. There is a PLL_LOCK signal to indicate that VCO has locked on to the input clock signal. Figure 2-11 shows the sysCLOCK PLL diagram.

Figure 2-11. PLL Diagram



For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

Spread Spectrum Clocking (SSC)

The PLL supports spread spectrum clocking to reduce peak EMI by using “down-spread” modulation. The spread spectrum operation will vary the output frequency (at 30KHz to 500KHz) in a range that is between its nominal value, down to a frequency that is a programmable 1%, 2%, or 3% lower than normal.

Digital Locked Loop (DLLs)

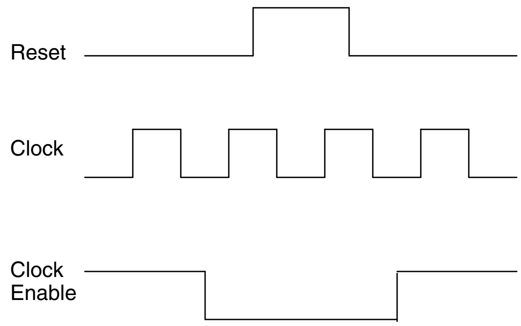
In addition to PLLs, the LatticeSC devices have up to 12 DLLs per device. DLLs assist in the management of clocks and strobes. DLLs are well suited to applications where the clock may be stopped or transferring jitter from input to output is important, for example forward clocked interfaces. PLLs are good for applications requiring the lowest output jitter or jitter filtering. All DLL outputs are routed as primary/edge clock sources.

The DLL has two independent clock outputs, CLKOP and CLKOS. These outputs can individually select one of the outputs from the tapped delay line. The CLKOS has optional fine phase shift and divider blocks to allow this output to be further modified, if required. The fine phase shift block allows the CLKOS output to phase shifted a further 45, 22.5 or 11.25 degrees relative to its normal position. LOCK output signal is asserted when the DLL is locked. The ALU HOLD signal setting allows users to freeze the DLL at its current delay setting.

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the low-to-high transition of the reset, as shown in Figure 2-16.

Figure 2-16. EBR Asynchronous Reset (Including GSR) Timing Diagram



If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becoming active.

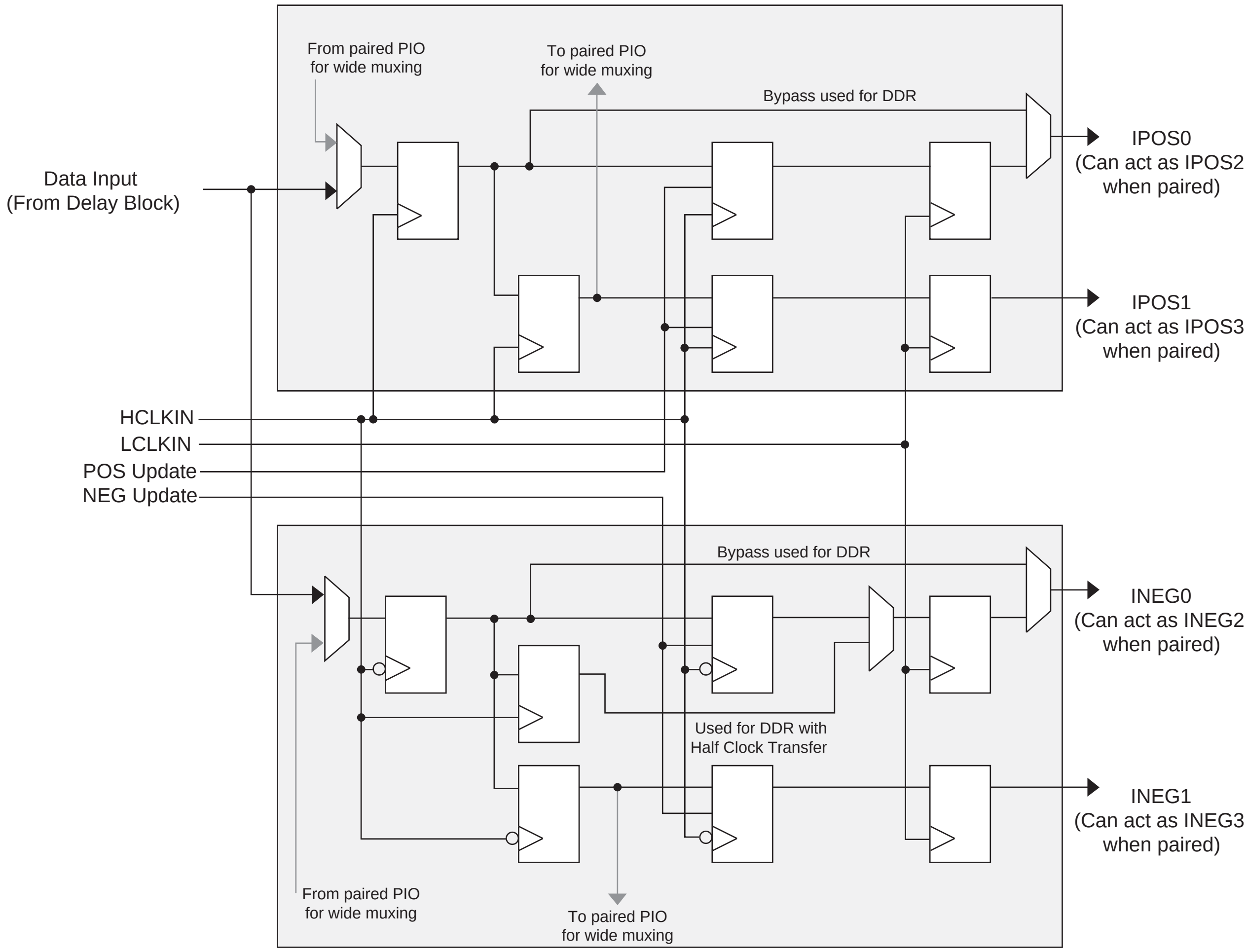
These instructions apply to all EBR RAM, ROM, FIFO and shift register implementations. For the EBR FIFO mode, the GSR signal is always enabled and the WE and RE signals act like the clock enable signals in Figure 2-16. The reset timing rules apply to the RPReset input vs. the RE input and the RST input vs. the WE and RE inputs. Both RST and RPReset are always asynchronous EBR inputs. For the EBR shift register mode, the GSR signal is always enabled and the local RESET pin is always asynchronous.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled. For more information about on-chip memory, see TN1094, On-Chip Memory Usage Guide for LatticeSC Devices.

Programmable I/O Cells (PIC)

Each PIC contains four PIOs connected to their respective PURESPEED I/O Buffer which are then connected to the PADs as shown in Figure 2-17. The PIO Block supplies the output data (DO) and the Tri-state control signal (TO) to PURESPEED I/O buffer, and receives input (DI) from the buffer. The PIO contains advanced capabilities to allow the support of speeds up to 2Gbps. These include dedicated shift and DDR logic and adaptive input logic. The dedicated resources simplify the design of robust interfaces.

Figure 2-21. Input DDR/Shift Register Block



Output Register Block

The output register block provides the ability to register signals from the core of the device before they are passed to the PURESPEED I/O buffers. The block contains a register for SDR operation and a group of registers for DDR and shift register operation. The output signal (DO) can be derived directly from one of the inputs (bypass mode), the SDR register or the DDR/shift register block. Figure 2-22 shows the diagram of the Output Register Block.

Output SDR Register/Latch Block

The SDR register operates on the positive edge of the high-speed clock. It has clock enable that is driven by the clock enable output signal generated by the control MUX. In addition it has a variety of programmable options for set/reset including, set or reset, asynchronous or synchronous Local Set Reset LSR (LSR has precedence over CE) and Global Set Reset GSR enable or disable. The register LSR input is driven from LSRO, which is generated from the PIO control MUX. The GSR inputs is driven from the GSR output of the PIO control MUX, which allows the global set-reset to be disabled on a PIO basis.

Output DDR/Shift Block

The DDR/Shift block contains registers and associated logic that support DDR and shift register functions using the high-speed clock and the associated transfer from the low-speed clock domain. It functions as a gearbox allowing low-speed parallel data from the FPGA fabric be output as a higher speed serial stream. Each PIO supports DDR and x2 shift functions. If desired PIOs A and B or C and D can be combined to form x4 shift functions. Figure 2-22 shows a simplified block diagram of the shift register block.

Table 2-9. Supported Input Standards

Input Standard	V_{REF} (Nom.)	V_{CCIO}[1] (Nom.)	On-chip Termination
Single Ended Interfaces			
LVTTL33[3]	—	3.3	None
LVCMOS 33, 25, 18, 15, 12[3]	—	3.3/2.5/1.8/1.5/1.2	None
PCI33, PCIX33, AGP1X33[3]	—	3.3	None
PCIX15	0.75	1.5[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
AGP2X33	1.32	—	None
HSTL18_I, II	0.9	1.8[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
HSTL18_III, IV	1.08	1.8[2]	None / V_{CCIO}: 50
HSTL15_I, II	0.75	1.5[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
HSTL15_III, IV	0.9	1.5[2]	None / V_{CCIO}: 50
SSTL33_I, II	1.5	3.3	None
SSTL25_I, II	1.25	2.5[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
SSTL18_I, II	0.9	1.8[2]	None / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
GTL+, GTL	1.0 / 0.8	1.5 / 1.2[2]	None / V_{CCIO}: 50
Differential Interfaces			
SSTL18D_I, II	—	1.8[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
SSTL25D_I, II	—	2.5[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
SSTL33D_I, II	—	3.3	None
HSTL15D_I, II	—	1.5[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
HSTL18D_I, II	—	1.8[2]	None / Diff: 120, 150, 220, 420/ Diff to V_{CMT}: 120, 150, 220, 420 / V_{CCIO} / 2: 50, 60/ V_{TT}: 60, 75, 120, 210
LVDS	—	—	None / Diff: 120, 150, 220, 240/ Diff to V_{CMT}: 120, 150, 220, 240
Mini-LVDS	—	—	None / Diff: 120, 150 / Diff to V_{CMT}: 120, 150
BLVDS25	—	—	None
MLVDS25	—	—	None
RSDS	—	—	None / Diff: 120, 150, 220, 240/ Diff to V_{CMT}: 120, 150, 220, 240
LVPECL33	—	≤2.5	None / Diff: 120, 150, 220, 240/ Diff to V_{CMT}: 120, 150, 220, 240

1. When not specified V_{CCIO} can be set anywhere in the valid operating range.
2. V_{CCIO} needed for on-chip termination to $V_{CCIO}/2$ or V_{CCIO} only. V_{CCIO} is not specified for off-chip termination or V_{TT} termination.
3. All ratioed input buffers and dedicated pin input buffers include hysteresis with a typical value of 50mV.

Figure 2-27. Output Termination Schemes

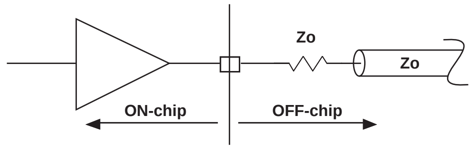
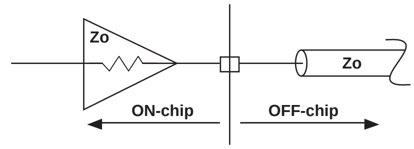
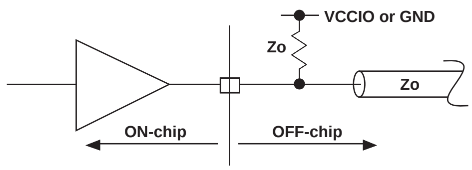
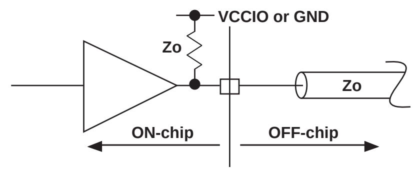
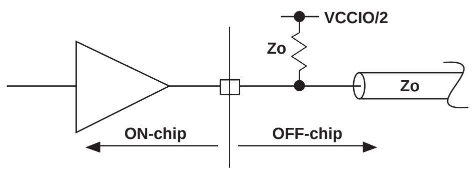
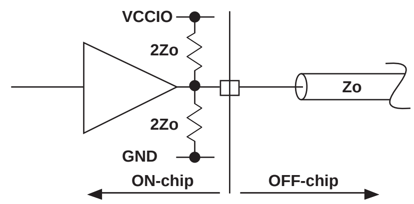
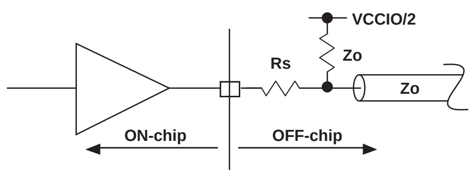
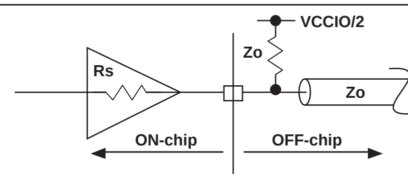
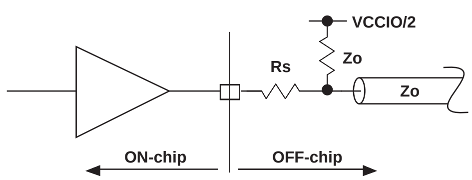
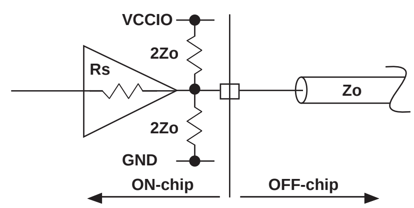
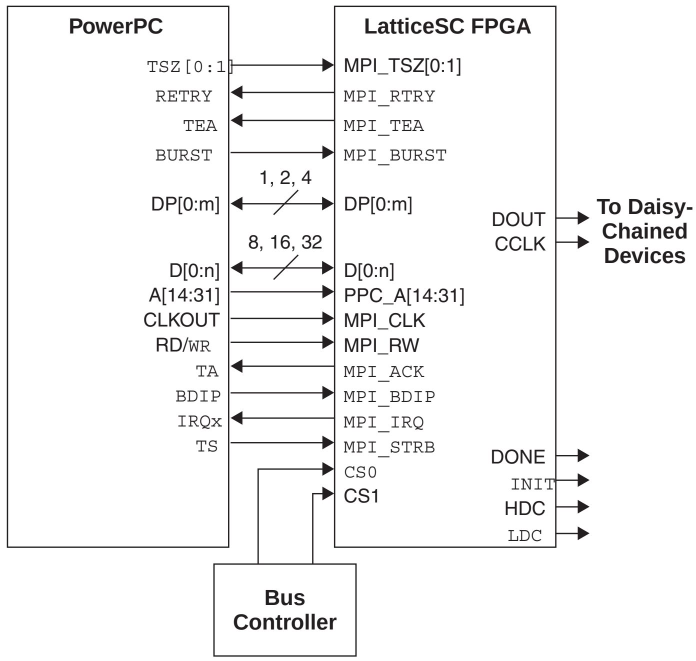
Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Series termination (controlled output impedance)		
Parallel termination to V_{CCIO}, or parallel driving end		
Parallel termination to $V_{CCIO}/2$ driving end		
Combined series + parallel termination to $V_{CCIO}/2$ at driving end (only series termination moved on-chip)		
Combined series + parallel to $V_{CCIO}/2$ driving end		

Figure 2-32. PowerPCI and MPI Schematic



Configuration and Testing

The following section describes the configuration and testing features of the LatticeSC family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeSC devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS33, 25 and 18 standards. For additional detail refer to technical information at the end of the data sheet.

Device Configuration

All LatticeSC devices contain three possible ports that can be used for device configuration. The serial port, which supports bit-wide configuration, and the sysCONFIG port that supports both byte-wide and serial configuration. The MPI port supports 8-bit, 16-bit or 32-bit configuration.

The serial port supports both the IEEE Std. 1149.1 Boundary Scan specification and the IEEE Std. 1532 In-System Configuration specification. The sysCONFIG port is a 20-pin interface with six of the I/Os used as dedicated pins and the rest being dual-use pins. When sysCONFIG mode is not used, these dual-use pins are available for general purpose I/O. All I/Os for the sysCONFIG and MPI ports are in I/O bank #1.

On power-up, the FPGA SRAM is ready to be configured with the sysCONFIG port active. The IEEE 1149.1 serial mode can be activated any time after power-up by sending the appropriate command through the TAP port. Once a configuration port is selected, that port is locked and another configuration port cannot be activated until the next re-initialization sequence. For additional detail refer to technical information at the end of the data sheet.

Power Supply Ramp Rates

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
t_{RAMP}	Power supply ramp rates for all power supplies	Over process, voltage, temperature	3.45	—	—	mV/µs
			—	—	75	ms

1. See the Power-up and Power-Down requirements section for more details on power sequencing.
2. From 0.5V to minimum operating voltage.

Hot Socketing Specifications[1]

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
I_{DK}	Programmable and dedicated Input or I/O leakage current[2, 3, 4, 5, 6]	0 <= V_{IN} <= V_{IH} (MAX)	—	—	±1500	µA
I_{HDIN}	SERDES average input current when device powered down and inputs driven[7]		—	—	4	mA

1. See Hot Socket power up/down information in Chapter 2 of this document.
2. Assumes monotonic rise/fall rates for all power supplies.
3. Sensitive to power supply sequencing as described in hot socketing section.
4. Assumes power supplies are between 0 and maximum recommended operations conditions.
5. IDK is additive to I_{PU}, I_{PD} or I_{BH}.
6. Represents DC conditions. For the first 20ns after hot insertion, current specification is 8 mA.
7. Assumes that the device is powered down with all supplies grounded, both P and N inputs driven by a CML driver with maximum allowed VDDOB of 1.575V, 8b/10b data and internal AC coupling.

DC Electrical Characteristics[5]

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.[3]	Typ.	Max.	Units
I_{IL}, I_{IH}[1]	Input or I/O Low leakage	$0 \le V_{IN} \le V_{IH}$ (MAX)	—	—	10	µA
I_{PU}	I/O Active Pull-up Current	$0 \le V_{IN} \le 0.7\ V_{CCIO}$	-30	—	-210	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) $\le V_{IN} \le V_{IH}$ (MAX)	30	—	210	µA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL}$ (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7V_{CCIO}$	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive Current	$0 \le V_{IN} \le V_{IH}$ (MAX)	—	—	210	µA
I_{BHLH}	Bus Hold High Overdrive Current	$0 \le V_{IN} \le V_{IH}$ (MAX)	—	—	-210	µA
I_{CL}	PCI Low Clamp Current	$-3 < V_{IN} \le -1$	-25 + (V_{IN} + 1)/0.015	—	—	mA
I_{CH}	PCI High Clamp Current	$V_{CC} + 4 > V_{IN} \ge V_{CC} + 1$	25 + (V_{IN} - V_{CC} -1)/ 0.015	—	—	mA
V_{BHT}	Bus Hold trip Points	$0 \le V_{IN} \le V_{IH}$ (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1	I/O Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{CCIP2} = 1.2V, V_{CCAUX} = 2.5, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C3[2]	Dedicated Input Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{CCIP2} = 1.2V, V_{CCAUX} = 2.5, V_{IO} = 0 to V_{IH} (MAX)	—	6	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. T_A 25°C, f = 1.0MHz
3. I_{PU}, I_{PD}, I_{BHLS} and I_{BHHS} have minimum values of 15 or -15µA if V_{CCIO} is set to 1.2V nominal.
4. This table does not apply to SERDES pins.
5. For programmable I/Os.

Initialization and Standby Supply Current

The table below indicates initialization and standby supply current while operating at 85°C junction temperature (T_J), which is the high end of the commercial temperature range, and 105°C, which is the high end of the industrial temperature range. This data assumes all outputs are tri-stated and all inputs are configured as LVCMOS and held at V_{CCIO} or GND. The remaining SERDES supply current for V_{DDIB} and V_{DDOB} is detailed in the SERDES section of this data sheet. For power at your design temperature, it is recommended to use the Power Calculator tool which is accessible in ispLEVER or can be used as a standalone tool. For more information on supply current, see the reference to additional technical documentation available at the end of this data sheet.

Over Recommended Operating Conditions

Symbol	Condition	Parameter	Device	25°C Typ.[1]	85°C Max.[2]		105°C Max.[2]	Units
				All	-5, -6	-7	-5, -6	
I_{CC}	(VCC = 1.2V +/- 5%)	Core Operating Power Supply Current	LFSC/M15	65	449	678	755	mA
			LFSC/M25	113	798	1255	1343	mA
			LFSC/M40	159	1178	2006	1981	mA
			LFSC/M80	276	2122	3827	3569	mA
			LFSC/M115	454	3376	—	5679	mA
	(VCC = 1.0V +/- 5%)	Core Operating Power Supply Current	LFSC/M15	45	312	471	524	mA
			LFSC/M25	79	554	872	933	mA
			LFSC/M40	110	818	1393	1375	mA
			LFSC/M80	191	1473	2658	2478	mA
			LFSC/M115	315	2344	—	3943	mA
I_{CC12}		1.2V Power Supply Current for Configuration Logic, FPGA PLL, SERDES PLL and SERDES Analog Supplies	LFSC/M15	23	39	59	35	mA
			LFSC/M25	25	50	78	56	mA
			LFSC/M40	31	78	133	89	mA
			LFSC/M80	50	108	195	123	mA
			LFSC/M115	65	131	—	154	mA
I_{CCAUX}		Auxiliary Operating Power Supply Current	LFSC/M15	7	12	19	14	mA
			LFSC/M25	9	16	25	18	mA
			LFSC/M40	12	23	39	25	mA
			LFSC/M80	13	25	45	23	mA
			LFSC/M115	16	27	—	26	mA
I_{CCIO} and I_{CCJ}		Bank Power Supply Current (per bank)	LFSC/M15	0.1	0.2	0.3	0.2	mA
			LFSC/M25	0.3	0.6	1.0	0.7	mA
			LFSC/M40	0.4	0.9	1.5	1.0	mA
			LFSC/M80	0.5	1.1	2.1	1.3	mA
			LFSC/M115	0.7	1.5	—	1.8	mA

1. I_{CC} is specified at T_J = 25°C and typical V_{CC}.
2. I_{CC} is specified at the respective commercial and industrial maximum T_J and V_{CC} limits.

LatticeSC/M sysCONFIG Port Timing

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
General Configuration Timing				
t_{SMODE}	M[3:0] Setup Time to INITN High	0	—	ns
t_{HMODE}	M[3:0] Hold Time from INITN High	600	—	ns
t_{RW}	RESETN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
t_{PGW}	PROGRAMN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
$f_{ESB\_CLK\_FRQ}$	System Bus ESB_CLK Frequency (No Wait States)	—	133	MHz
sysCONFIG Master Parallel Configuration Mode				
t_{SMB}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMB}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMB}	RCLK Low Time (Non-compressed Bitstreams)	0.5	0.5	CCLK periods
	RCLK Low Time (Compressed Bitstreams)	0.5	7.5	CCLK periods
t_{CHMB}	RCLK High Time	0.5	0.5	CCLK periods
sysCONFIG SPI Port				
t_{CFGX}	INITN High to CSCK Low	—	80	ns
t_{CSSPI}	INITN High to CSSPIN Low	0	2	µs
t_{SCK}	CSCK Low before CSSPIN Low	0	—	ns
t_{SOCDO}	CSCK Low to Output Valid	—	15	ns
t_{CSPID}	CSSPIN Low to CSCK high Setup Time	—	15	ns
f_{MAXSPI}	Max CCLK Frequency - SPI Flash Fast Read Opcode (0x0B) (SPIFASTN=0)	—	50	MHz
t_{SUSPI}	SOSPI/D0 Data Setup Time Before CSCK	7	—	ns
t_{HSPI}	SOSPI/D0 Data Hold Time After CSCK	2	—	ns
	Master Clock Frequency	Selected value - 30%	Selected value + 30%	MHz
	Duty Cycle	40	60	%
sysCONFIG Master Serial Configuration Mode				
t_{SMS}	DIN Setup Time	4.4	—	ns
t_{HMS}	DIN Hold Time	0	—	ns
f_{CMS}	CCLK Frequency (No Divider)	90	190	MHz
f_{C_DIV}	CCLK Frequency (Div 128)	0.70	1.48	MHz
t_D	CCLK to DOUT Delay	—	7.5	ns
sysCONFIG Master Parallel Configuration Mode				
t_{AVMP}	RCLK to Address Valid	—	10	ns
t_{SMP}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMP}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMP}	RCLK Low Time (Non-compressed Bitstream)	7.5	7.5	CCLK periods
	RCLK Low Time (Compressed Bitstream)	0.5	63.5	
t_{CHMP}	RCLK High Time	0.5	0.5	CCLK periods
t_{DMP}	CCLK to DOUT	—	7.5	ns

Signal Descriptions (Cont.)

Signal Name	I/O	Description
MPI_STRBN	I	Driven active low indicates the start of a transaction on the PowerPC bus. MPI will strobe the address bus at next rising edge of clock.
MPI_ADDR[31:14]	I	Address bus driven by a PowerPC bus master. Only 18-bit width is needed. It has to be the least significant bit of the PowerPC 32-bit address A[31:14].
MPI_DAT[n:0]	I/O	Selectable data bus width from 8, and 16-bit. Driven by a bus master in a write transaction. Driven by MPI in a read transaction.
MPI_PAR[m:0]	I/O	Selectable parity bus width from 1, 2, and 3-bit. MPI_DP[0] for MPI_D[7:0], MPI_DP[1] for MPI_D[15:8] and MPI_DP[2] for MPI_D[23:16].
MPI_TA	O	Transfer acknowledge. Driven active low indicates that MPI received the data on the write cycle or returned data on the read cycle.
MPI_TEA	O	Transfer Error Acknowledge. Driven active low indicates that MPI detects a bus error on the internal system bus for current transaction.
MPI_RETRY	O	Active low MPI Retry requests the MPC860 to relinquish the bus and retry the cycle.
Multi-chip Alignment (User I/O if not used.)		
MCA_DONE_OUT	O	Multi-chip alignment done output (to second MCA chip)
MCA_DONE_IN	I	Multi-chip alignment done input (from second MCA chip)
MCA_CLK_P[1:2]_OUT	O	Multi-chip alignment clock [1:2] output (sourced by MCA master chip)
MCA_CLK_P[1:2]_IN	I	Multi-chip alignment clock [1:2] input (from MCA master chip
TEMP	—	Temperature sensing diode pin. Dedicated pin. Accuracy is typically +/- 10°C.
Miscellaneous Dedicated Pins		
XRES	—	External reference resistor between this pin and ground. The reference resistor is used to calibrate the programmable terminating resistors used in the I/Os. Dedicated pin. Value: 1K ± 1% ohm.
DIFFRx	—	Only used if a differential driver is used in a bank. This DIFFRx must be connected to ground via an external 1K ±1% ohm resistor for all banks that have a differential driver.
SERDES Block (Dedicated Pins)		
[A:D]_HDINPx_[L/R]	I	High-speed input (positive) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDINNx_[L/R]	I	High-speed input (negative) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDOUTPx_[L/R]	O	High-speed output (positive) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDOUTNx_[L/R]	O	High-speed output (negative) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_REFCLKP_[L/R]	I	Ref clock input (positive), aux channel on left [L] or right [R] side of device.
[A:D]_REFCLKN_[L/R]	I	Ref clock input (negative), aux channel on left [L] or right [R] side of device.

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

	LFSC/M15			LFSC/M25		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
N3	PL27A	6		PL30A	6	
P3	PL27B	6		PL30B	6	
P4	PL27C	6	PCLKT6_3	PL30C	6	PCLKT6_3
P2	PL28A	6		PL31A	6	
R2	PL28B	6		PL31B	6	
T3	PL28C	6	PCLKT6_2	PL31C	6	PCLKT6_2
R3	PL28D	6	PCLKC6_2	PL31D	6	PCLKC6_2
P1	PL31A	6		PL34A	6	
R1	PL31B	6		PL34B	6	
R5	PL31C	6	VREF1_6	PL34C	6	VREF1_6
R4	PL31D	6		PL34D	6	
T2	PL32A	6		PL35A	6	
U2	PL32B	6		PL35B	6	
T1	PL33A	6		PL38A	6	
U1	PL33B	6		PL38B	6	
V1	PL35A	6		PL42A	6	
W1	PL35B	6		PL42B	6	
V6	PL35D	6	DIFFR_6	PL42D	6	DIFFR_6
V2	PL36A	6		PL43A	6	
W2	PL36B	6		PL43B	6	
Y1	PL37A	6		PL44A	6	
AA1	PL37B	6		PL44B	6	
AB1	PL39A	6		PL48A	6	
AC1	PL39B	6		PL48B	6	
Y5	PL40A	6		PL49A	6	
Y6	PL40B	6		PL49B	6	
AD2	PL41A	6		PL51A	6	
AE2	PL41B	6		PL51B	6	
AB5	PL41D	6	VREF2_6	PL51D	6	VREF2_6
AC3	PL43A	6		PL52A	6	
AD3	PL43B	6		PL52B	6	
AF1	PL44A	6		PL55A	6	
AG1	PL44B	6		PL55B	6	
AB6	PL44C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F	PL55C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F
AC5	PL44D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F	PL55D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F
AF2	PL45A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E	PL57A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E
AG2	PL45B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E	PL57B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E
AC6	PL45C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A	PL57C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A
AC7	PL45D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A	PL57D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A
AE4	XRES	-		XRES	-	
AG4	VCC12	-		VCC12	-	
AD5	TEMP	6		TEMP	6	
AF5	VCC12	-		VCC12	-	
AH1	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B
AJ1	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

	LFSC/M15			LFSC/M25		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
R29	PR28B	3		PR31B	3	
P29	PR28A	3		PR31A	3	
P27	PR27C	3	PCLKT3_3	PR30C	3	PCLKT3_3
N29	PR27B	3		PR30B	3	
N28	PR27A	3		PR30A	3	
R25	PR26D	3	PCLKC3_1	PR29D	3	PCLKC3_1
R26	PR26C	3	PCLKT3_1	PR29C	3	PCLKT3_1
R28	PR26B	3	PCLKC3_0	PR29B	3	PCLKC3_0
P28	PR26A	3	PCLKT3_0	PR29A	3	PCLKT3_0
N27	PR24D	2	PCLKC2_2	PR27D	2	PCLKC2_2
P26	PR24C	2	PCLKT2_2	PR27C	2	PCLKT2_2
L30	PR24B	2	PCLKC2_0	PR27B	2	PCLKC2_0
K30	PR24A	2	PCLKT2_0	PR27A	2	PCLKT2_0
J30	PR23B	2	PCLKC2_1	PR26B	2	PCLKC2_1
H30	PR23A	2	PCLKT2_1	PR26A	2	PCLKT2_1
M26	PR22D	2	DIFFR_2	PR25D	2	DIFFR_2
M25	PR22C	2	VREF1_2	PR25C	2	VREF1_2
G29	PR22B	2		PR25B	2	
F29	PR22A	2		PR25A	2	
H28	PR19D	2		PR22D	2	
J28	PR19C	2		PR22C	2	
E30	PR19B	2		PR22B	2	
E29	PR19A	2		PR22A	2	
L26	PR18D	2	VREF2_2	PR18D	2	VREF2_2
L25	PR18C	2		PR18C	2	
F28	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
G28	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
K26	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
K25	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
D30	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
D29	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
G26	PR15D	2		PR16D	2	
H26	PR15C	2		PR16C	2	
E28	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
D28	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
J25	VCCJ	-		VCCJ	-	
H25	TDO	-	TDO	TDO	-	TDO
J26	TMS	-		TMS	-	
G25	TCK	-		TCK	-	
G24	TDI	-		TDI	-	
F26	PROGRAMN	1		PROGRAMN	1	
H24	MPIIRQN	1	CFGIRQN/MPI_IRQ_N	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
F25	CCLK	1		CCLK	1	
D27	VCC12	-		VCC12	-	
E26	VCC12	-		VCC12	-	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

	LFSC/M15			LFSC/M25		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
D14	PT15B	1	A15/MPI_ADDR29	PT25B	1	A15/MPI_ADDR29
D13	PT15A	1	A17/MPI_ADDR31	PT25A	1	A17/MPI_ADDR31
F12	PT13D	1	A19/MPI_TSIZ1	PT24D	1	A19/MPI_TSIZ1
F13	PT13C	1	A20/MPI_BDIP	PT24C	1	A20/MPI_BDIP
B12	PT11B	1	A18/MPI_TSIZ0	PT24B	1	A18/MPI_TSIZ0
B11	PT11A	1	MPI_TEA	PT24A	1	MPI_TEA
E12	PT10D	1	D14/MPI_DATA14	PT23D	1	D14/MPI_DATA14
D12	PT10C	1	DP1/MPI_PAR1	PT23C	1	DP1/MPI_PAR1
G10	PT9B	1	A21/MPI_BURST	PT23B	1	A21/MPI_BURST
G9	PT9A	1	D15/MPI_DATA15	PT23A	1	D15/MPI_DATA15
C10	A_VDDIB3_L	-		A_VDDIB3_L	-	
E9	VCC12	-		VCC12	-	
B10	A_HDINP3_L	-	PCS 360 CH 3 IN P	A_HDINP3_L	-	PCS 360 CH 3 IN P
B9	A_HDINN3_L	-	PCS 360 CH 3 IN N	A_HDINN3_L	-	PCS 360 CH 3 IN N
A10	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
D9	VCC12	-		VCC12	-	
A9	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
C9	A_VDDOB3_L	-		A_VDDOB3_L	-	
A8	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
C8	A_VDDOB2_L	-		A_VDDOB2_L	-	
A7	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
E8	VCC12	-		VCC12	-	
B8	A_HDINN2_L	-	PCS 360 CH 2 IN N	A_HDINN2_L	-	PCS 360 CH 2 IN N
B7	A_HDINP2_L	-	PCS 360 CH 2 IN P	A_HDINP2_L	-	PCS 360 CH 2 IN P
C7	A_VDDIB2_L	-		A_VDDIB2_L	-	
D8	VCC12	-		VCC12	-	
C6	A_VDDIB1_L	-		A_VDDIB1_L	-	
E7	VCC12	-		VCC12	-	
B6	A_HDINP1_L	-	PCS 360 CH 1 IN P	A_HDINP1_L	-	PCS 360 CH 1 IN P
B5	A_HDINN1_L	-	PCS 360 CH 1 IN N	A_HDINN1_L	-	PCS 360 CH 1 IN N
A6	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
D7	VCC12	-		VCC12	-	
A5	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
C5	A_VDDOB1_L	-		A_VDDOB1_L	-	
A4	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
C4	A_VDDOB0_L	-		A_VDDOB0_L	-	
A3	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
E6	VCC12	-		VCC12	-	
B4	A_HDINN0_L	-	PCS 360 CH 0 IN N	A_HDINN0_L	-	PCS 360 CH 0 IN N
B3	A_HDINP0_L	-	PCS 360 CH 0 IN P	A_HDINP0_L	-	PCS 360 CH 0 IN P
C3	A_VDDIB0_L	-		A_VDDIB0_L	-	
D6	VCC12	-		VCC12	-	
L5	NC	-		PL21A	7	
M5	NC	-		PL21B	7	
G2	NC	-		PL20A	7	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
Y24	PL48C	6		PL61C	6	
Y23	PL48D	6		PL61D	6	
AD29	PL49A	6		PL62A	6	
AD30	PL49B	6		PL62B	6	
AF28	PL49C	6		PL62C	6	
AE28	PL49D	6		PL62D	6	
AC28	PL51A	6		PL65A	6	
AD28	PL51B	6		PL65B	6	
AB26	PL51C	6		PL65C	6	
AC26	PL51D	6	VREF2_6	PL65D	6	VREF2_6
AC32	PL52A	6		PL66A	6	
AD32	PL52B	6		PL66B	6	
AA24	PL52C	6		PL66C	6	
AA23	PL52D	6		PL66D	6	
AE30	PL53A	6		PL67A	6	
AE29	PL53B	6		PL67B	6	
AC25	PL53C	6		PL67C	6	
AB25	PL53D	6		PL67D	6	
AE31	PL55A	6		PL69A	6	
AE32	PL55B	6		PL69B	6	
AE26	PL55C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F	PL69C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F
AE27	PL55D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F	PL69D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F
AF32	PL56A	6		PL70A	6	
AF31	PL56B	6		PL70B	6	
AC24	PL56C	6		PL70C	6	
AD25	PL56D	6		PL70D	6	
AG32	PL57A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E	PL71A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E
AG31	PL57B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E	PL71B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E
AC23	PL57C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A	PL71C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A
AD24	PL57D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A	PL71D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A
AH32	XRES	-		XRES	-	
AH31	TEMP	6		TEMP	6	
AJ32	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B
AK32	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B
AF27	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D
AG28	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D
AK31	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C
AL31	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C
AE25	PB4C	5		PB4C	5	
AE24	PB4D	5		PB4D	5	
AK30	PB5A	5		PB5A	5	
AL30	PB5B	5		PB5B	5	
AD23	PB5C	5		PB5C	5	
AE23	PB5D	5	VREF1_5	PB5D	5	VREF1_5
AK29	PB7A	5		PB7A	5	
AL29	PB7B	5		PB7B	5	
AF26	PB7C	5		PB7C	5	
AF25	PB7D	5		PB7D	5	
AJ28	PB8A	5		PB8A	5	
AK28	PB8B	5		PB8B	5	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2]

	LFSC/M40			LFSC/M80		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
G27	A_REFCLKP_L	-		A_REFCLKP_L	-	
H27	A_REFCLKN_L	-		A_REFCLKN_L	-	
H25	VCC12	-		VCC12	-	
H26	RESP_ULC	-		RESP_ULC	-	
B33	RESETN	1		RESETN	1	
C34	TSALLN	1		TSALLN	1	
D34	DONE	1		DONE	1	
C33	INITN	1		INITN	1	
J27	M0	1		M0	1	
K27	M1	1		M1	1	
M26	M2	1		M2	1	
L26	M3	1		M3	1	
F30	PL16A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B	PL16A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B
G30	PL16B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B	PL16B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B
H28	PL16C	7		PL16C	7	
J28	PL16D	7		PL16D	7	
F31	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D
G31	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D
N25	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A
P25	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A
D33	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C
E33	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C
H29	PL18C	7		PL18C	7	
J29	PL18D	7	VREF2_7	PL18D	7	VREF2_7
F32	PL21A	7		PL20A	7	
G32	PL21B	7		PL20B	7	
P26	PL21C	7		PL20C	7	
N26	PL21D	7		PL20D	7	
H30	PL22A	7		PL21A	7	
J30	PL22B	7		PL21B	7	
L28	PL22C	7		PL21C	7	
M28	PL22D	7		PL21D	7	
J31	PL23A	7		PL29A	7	
K31	PL23B	7		PL29B	7	
L27	PL23C	7	VREF1_7	PL29C	7	VREF1_7
M27	PL23D	7	DIFFR_7	PL29D	7	DIFFR_7
J32	PL25A	7		PL31A	7	
K32	PL25B	7		PL31B	7	
L29	PL25C	7		PL31C	7	
M29	PL25D	7		PL31D	7	
H33	PL26A	7		PL33A	7	
J33	PL26B	7		PL33B	7	
N27	PL26C	7		PL33C	7	
P27	PL26D	7		PL33D	7	
K33	PL27A	7		PL35A	7	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AG18	PB42C	5		PB61C	5	
AF18	PB42D	5		PB61D	5	
AP19	PB43A	5		PB63A	5	
AP18	PB43B	5		PB63B	5	
AJ18	PB43C	5		PB63C	5	
AH18	PB43D	5		PB63D	5	
AP17	PB45A	4		PB65A	4	
AP16	PB45B	4		PB65B	4	
AJ17	PB45C	4		PB65C	4	
AH17	PB45D	4		PB65D	4	
AN17	PB46A	4		PB66A	4	
AN16	PB46B	4		PB66B	4	
AE17	PB46C	4		PB66C	4	
AD17	PB46D	4		PB66D	4	
AK17	PB47A	4		PB67A	4	
AK16	PB47B	4		PB67B	4	
AG17	PB47C	4		PB67C	4	
AF17	PB47D	4		PB67D	4	
AM16	PB49A	4		PB69A	4	
AM15	PB49B	4		PB69B	4	
AJ15	PB49C	4		PB69C	4	
AJ14	PB49D	4		PB69D	4	
AL16	PB50A	4		PB70A	4	
AL15	PB50B	4		PB70B	4	
AG16	PB50C	4		PB70C	4	
AF16	PB50D	4		PB70D	4	
AP15	PB51A	4		PB71A	4	
AP14	PB51B	4		PB71B	4	
AH15	PB51C	4		PB71C	4	
AH14	PB51D	4		PB71D	4	
AN15	PB53A	4	PCLKT4_2	PB74A	4	PCLKT4_2
AN14	PB53B	4	PCLKC4_2	PB74B	4	PCLKC4_2
AE16	PB53C	4	PCLKT4_7	PB74C	4	PCLKT4_7
AD16	PB53D	4	PCLKC4_7	PB74D	4	PCLKC4_7
AK15	PB54A	4	PCLKT4_1	PB75A	4	PCLKT4_1
AK14	PB54B	4	PCLKC4_1	PB75B	4	PCLKC4_1
AG15	PB54C	4	PCLKT4_6	PB75C	4	PCLKT4_6
AG14	PB54D	4	PCLKC4_6	PB75D	4	PCLKC4_6
AM13	PB55A	4	PCLKT4_0	PB77A	4	PCLKT4_0
AM12	PB55B	4	PCLKC4_0	PB77B	4	PCLKC4_0
AJ12	PB55C	4	VREF2_4	PB77C	4	VREF2_4
AJ11	PB55D	4		PB77D	4	
AL13	PB57A	4	PCLKT4_5	PB79A	4	PCLKT4_5
AL12	PB57B	4	PCLKC4_5	PB79B	4	PCLKC4_5
AH12	PB57C	4		PB79C	4	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
J1	PR25B	2		PR38B	2	
K1	PR25A	2		PR38A	2	
V12	PR24D	2		PR34D	2	
U12	PR24C	2		PR34C	2	
K2	PR24B	2		PR34B	2	
J2	PR24A	2		PR34A	2	
R10	PR22D	2		PR30D	2	
T10	PR22C	2		PR30C	2	
L5	PR22B	2		PR30B	2	
K5	PR22A	2		PR30A	2	
P9	PR21D	2		PR26D	2	
N9	PR21C	2		PR26C	2	
L6	PR21B	2		PR26B	2	
K6	PR21A	2		PR26A	2	
M8	PR20D	2		PR19D	2	
M9	PR20C	2		PR19C	2	
H1	PR20B	2		PR19B	2	
G1	PR20A	2		PR19A	2	
U14	PR18D	2	VREF2_2	PR18D	2	VREF2_2
T14	PR18C	2		PR18C	2	
H2	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
G2	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
P10	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
N10	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
H3	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
G3	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
R11	PR16D	2		PR15D	2	
P11	PR16C	2		PR15C	2	
J5	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
J6	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
P18	VCCJ	-		VCCJ	-	
P19	TDO	-	TDO	TDO	-	TDO
R21	TMS	-		TMS	-	
P20	TCK	-		TCK	-	
P12	TDI	-		TDI	-	
P17	PROGRAMN	1		PROGRAMN	1	
P21	MPIIRQN	1	CFGIRQN/MPI_IRQ_N	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
P13	CCLK	1		CCLK	1	
H10	RESP_URC	-		RESP_URC	-	
N13	VCC12	-		VCC12	-	
H9	A_REFCLKN_R	-		A_REFCLKN_R	-	
G9	A_REFCLKP_R	-		A_REFCLKP_R	-	
F2	VCC12	-		VCC12	-	
H4	A_VDDIB0_R	-		A_VDDIB0_R	-	
C1	A_HDINP0_R	-	PCS 3E0 CH 0 IN P	A_HDINP0_R	-	PCS 3E0 CH 0 IN P